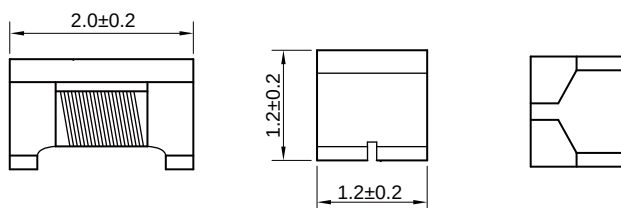




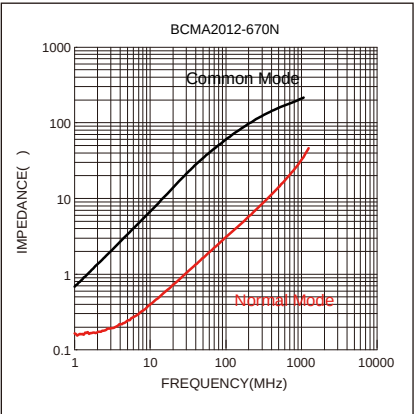
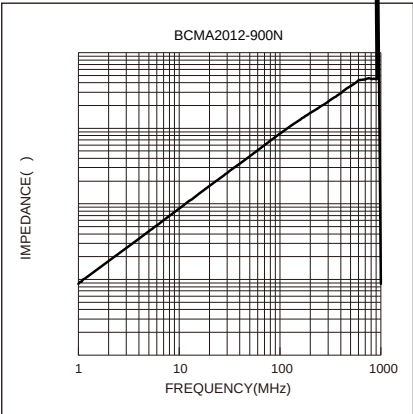
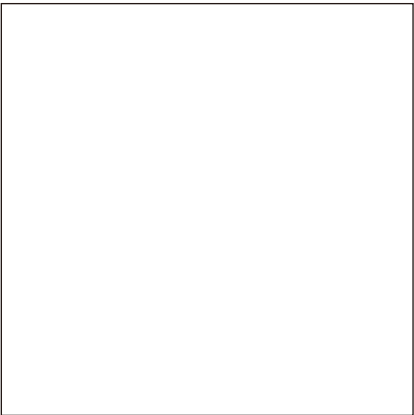
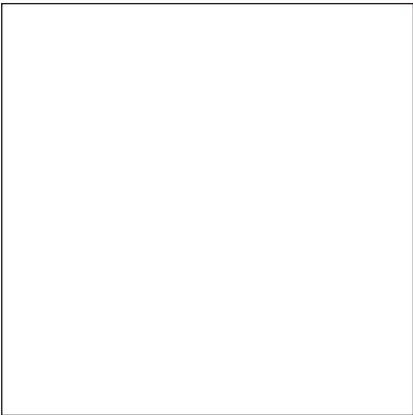
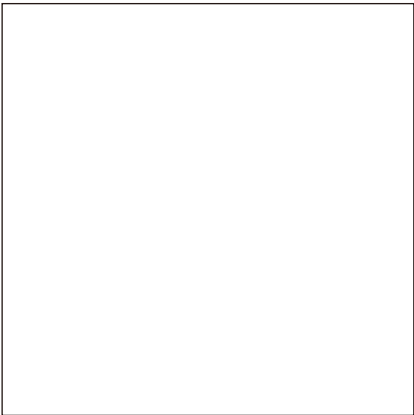
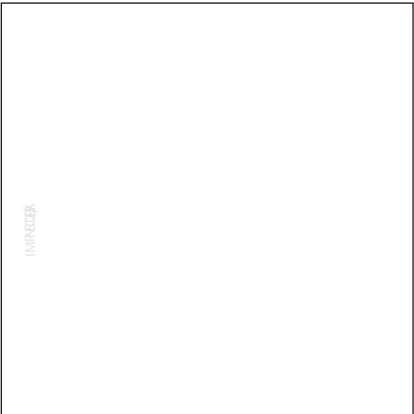
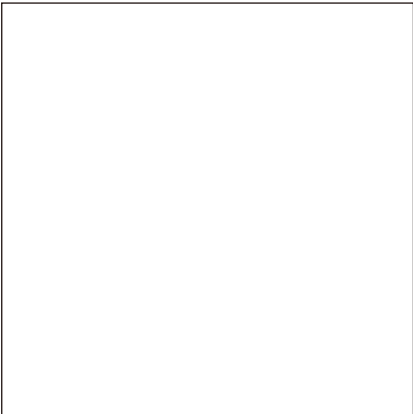
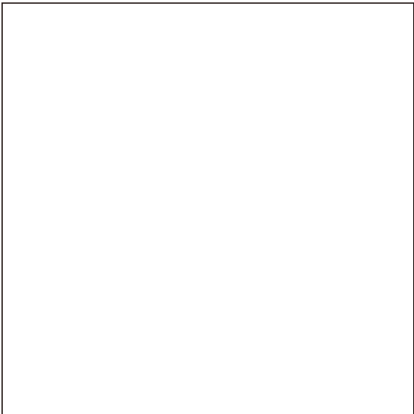
- [illegible]

Dimensions: [mm]

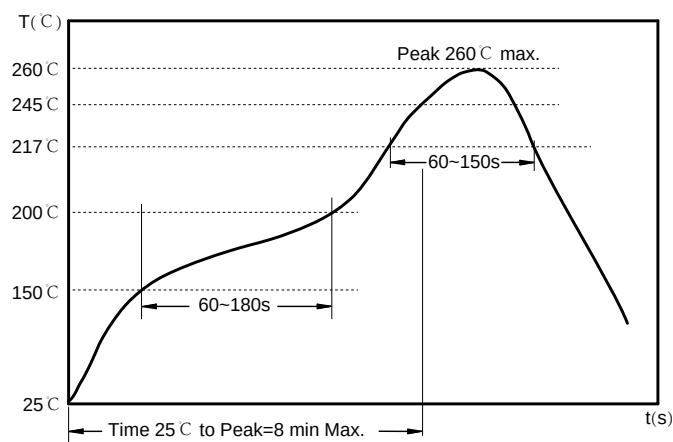


Electrical Properties:

Typical Electrical Characteristics:



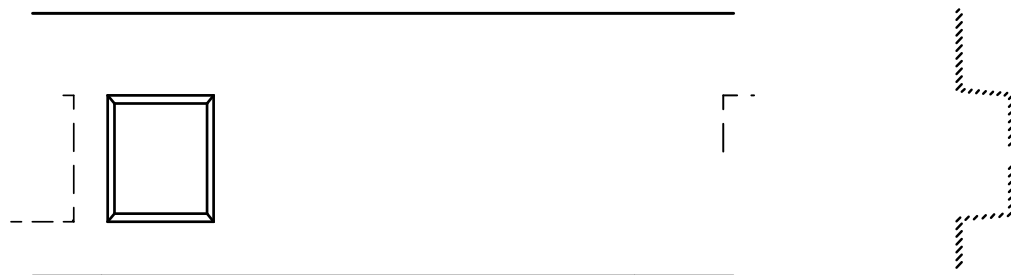
Soldering Reflow:



Preheat condition: 150 ~200 °C / 60~180 sec.
Allowed time above 217 °C : 60~150 sec.
Max temperature: 260 °C .

Packaging Information:

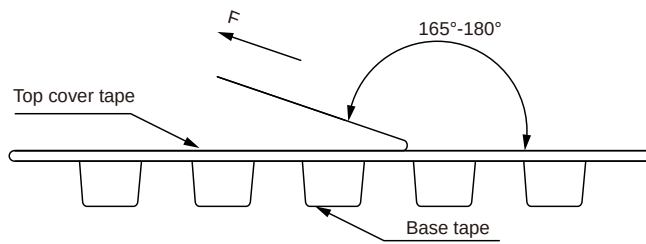
Tape Dimension :



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
BCMA2012	1.50±0.1	2.35±0.1	1.5±0.1	4.0±0.1	4.0±0.1	8.0±0.3	1.45±0.1	1.75±0.1	0.22±0.05

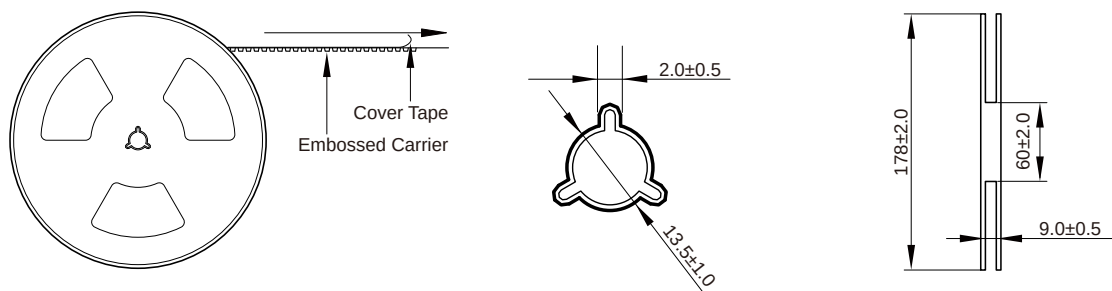


Peel force of top cover tape:

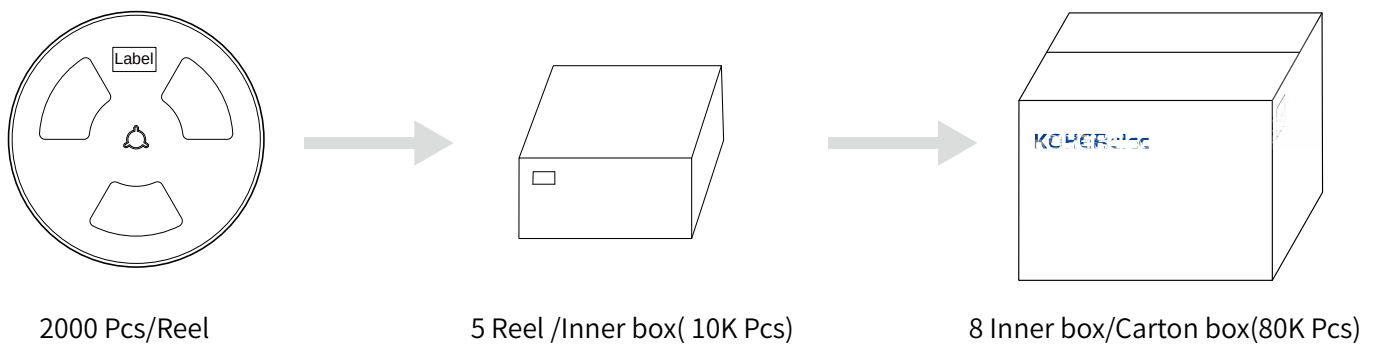


The peel force of top cover tape shall be between 0.14 to 0.78 N

Reel Dimension: [mm]



Packaging Quantity:



Cautions and Warnings:

Storage Conditions:

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max). If the storage period elapses, the soldering of the terminal electrodes may deteriorate. The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components. The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
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